

TOSHIBA Field Effect Transistor Silicon P-Channel MOS Type (U-MOS IV)

TPCF8304

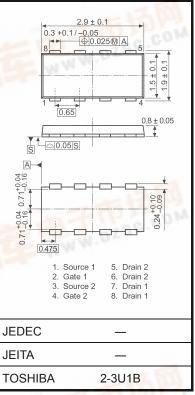
Notebook PC Applications Portable Equipment Applications

- Low drain-source ON resistance: $RDS(ON) = 60 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance: $|Y_{fs}| = 5.9 \text{ S (typ.)}$
- Low leakage current: $I_{DSS} = -10 \,\mu\text{A} \,(\text{max}) \,(V_{DS} = -30 \,\text{V})$
- Enhancement model: $V_{th} = -0.8$ to -2.0 V, $(V_{DS} = -10$ V, $I_{D} = -1$ mA)

Absolute Maximum Ratings (Ta = 25°C)

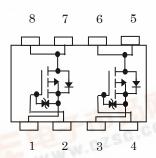
Cha	Symbol	Rating	Unit		
Drain-source voltag	V_{DSS}	-30	V		
Drain-gate voltage	V _{DGR}	-30	V		
Gate-source voltage	V _{GSS}	±20	V		
Drain current	DC (Note 1)	ΙD	-3.2	Α	
Dialii Curient	Pulse (Note 1)	VDGR -30 VGSS ±20 (Note 1) ID -3.2 (Note 1) IDP -12.8 ice operation (Note 3a) PD (1) 1.35 ice value at tion (Note 3b) PD (2) 1.12 ice operation (Note 3a) PD (1) 0.53 ice value at tion (Note 3b) PD (2) 0.33	A		
Drain power dissipation (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	P _{D (1)}	1.35	W	
	Single-device value at dual operation (Note 3b)	P _{D (2)}	1.12		
Drain power dissipation	Single-device operation (Note 3a)	P _{D (1)}	0.53	12 1	
(t = 5 s) (Note 2b)	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.33		
Single-pulse avalar	nche energy (Note 4)	E _{AS}	0.67	mJ	
Avalanche current	THE WHAT	I _{AR}	-1.6	Α	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E _{AR}	0.11	mJ	
Channel temperatu	T _{ch}	150	°C		
Storage temperatu	T _{stg}	-55~150	°C		

Unit: mm



Weight: 0.011 g (typ.)

Circuit Configuration



Note: For Notes 1 to 6, see the next page.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Caution: This transistor is an electrostatic-sensitive device. Handle with care.

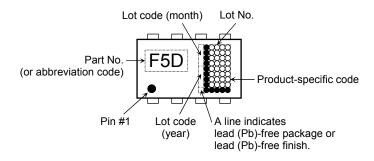


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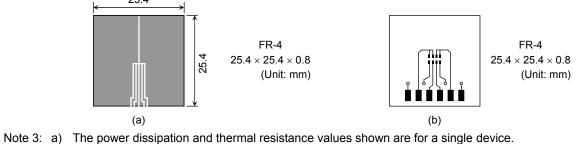
Thermal Characteristics

Chara	Symbol	Max	Unit		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	92.6	- °C/W	
(t = 5 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	111.6		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	235.8	°C/W	
(t = 5 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	378.8	C/VV	

Marking (Note 6)



- Note 1: Ensure that the channel temperature does not exceed 150°C.
- Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)



- 25.4 FR-4 25.4 $25.4\times25.4\times0.8$ (Unit: mm)
- (During single-device operation, power is applied to one device only.)
 - b) The power dissipation and thermal resistance values shown are for a single device. (During dual operation, power is evenly applied to both devices.)
- Note 4: $V_{DD} = -24~V$, $T_{ch} = 25^{\circ}C$ (initial), L = 0.2~mH, $R_G = 25~\Omega$, $I_{AR} = -1.6~A$
- Note 5: Repetitive rating; pulse width limited by max channel temperature
- Note 6: to the lower left of the Part No. marking indicates Pin 1.

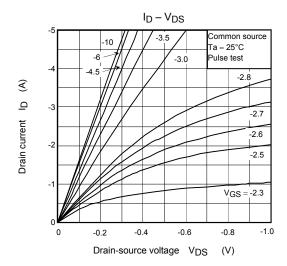
Electrical Characteristics (Ta = 25°C)

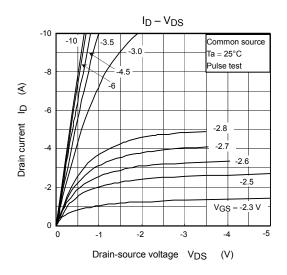
Ch	naracteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-off curr	ent	I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V	_	_	-10	μА
Drain-source breakdown voltage		V _{(BR) DSS}	$I_D = -10$ mA, $V_{GS} = 0$ V	-30	_	_	· V
Dialii-source bre	akdowii voitage	V _{(BR) DSX}	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-15 — —		_	
Gate threshold v	oltage	V _{th}	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	-0.5	_	-1.2	V
Drain aguras ON	Drain-source ON resistance		V _{GS} = -4.5 V, I _D = -1.6 A	-	80	105	mΩ
Diain-source ON	resistance	R _{DS} (ON)	$V_{GS} = -10 \text{ V}, I_D = -1.6 \text{ A}$	_	60	72	1115.2
Forward transfer	admittance	Y _{fs}	V _{DS} = -10 V, I _D = -1.6 A 2.9 5.9		_	S	
Input capacitance		C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	600	_	pF
Reverse transfer	Reverse transfer capacitance			_	60	_	
Output capacitance		Coss		_	70	_	
Switching time	Rise time	t _r	VGS 0 V 1D = -1.6 A VOUT	-	5.3	_	
	Turn-on time	t _{on}		_	12	_	
	Fall time	t _f		_	8.4	_	ns
	Turn-off time	t _{off}	$V_{DD} \simeq -15 \text{ V}$ Duty $\leq 1\%$, $t_W = 10 \mu\text{s}$	_	34	_	
Total gate charge (gate-source plus gate-drain)		Qg	V _{DD} ≈ -24 V, V _{GS} = -10 V,	_	14		
Gate-source charge 1		Q _{gs1}	$I_D = -3.2 \text{ A}$	_	1.4	_	nC
Gate-drain ("Miller") charge		Q _{gd}		_	2.7	_	

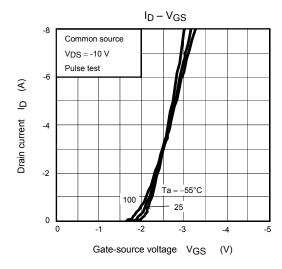
Source-Drain Ratings and Characteristics (Ta = 25°C)

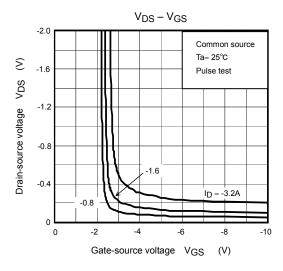
Characteris	tic	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	-12.8	Α
Forward voltage (diode)		V_{DSF}	$I_{DR} = -3.2 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

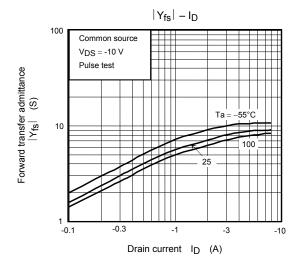
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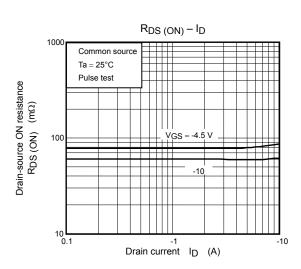


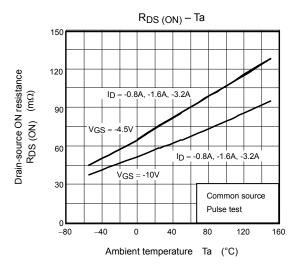


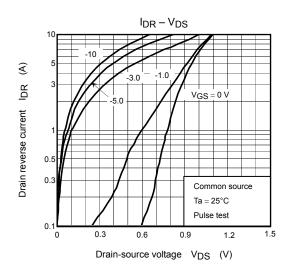


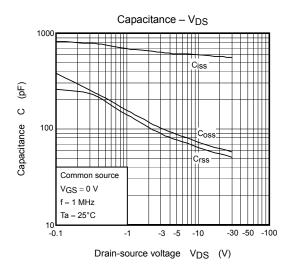


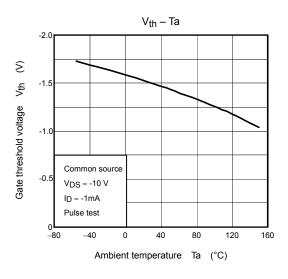


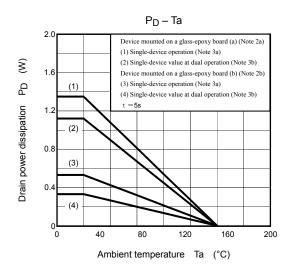


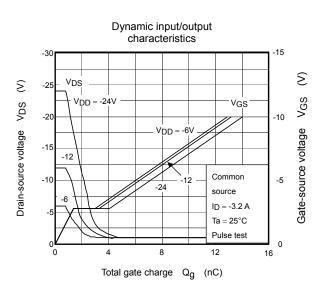


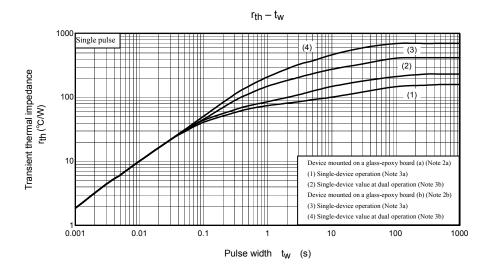


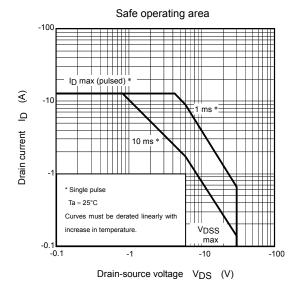












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